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Harnden et al.

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(54) **PORTION OF A MATRIX FOR SURFACE MOUNT PACKAGE LEADFRAME**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

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(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/182; 29/622,
29/827; 174/52.2, 52.4; 206/713, 714, 715,
716, 727, 728; 257/667, 668; 333/185;
428/573

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(57) **CLAIM**

The ornamental design for a portion of a matrix for surface mount package leadframe, as shown and described.

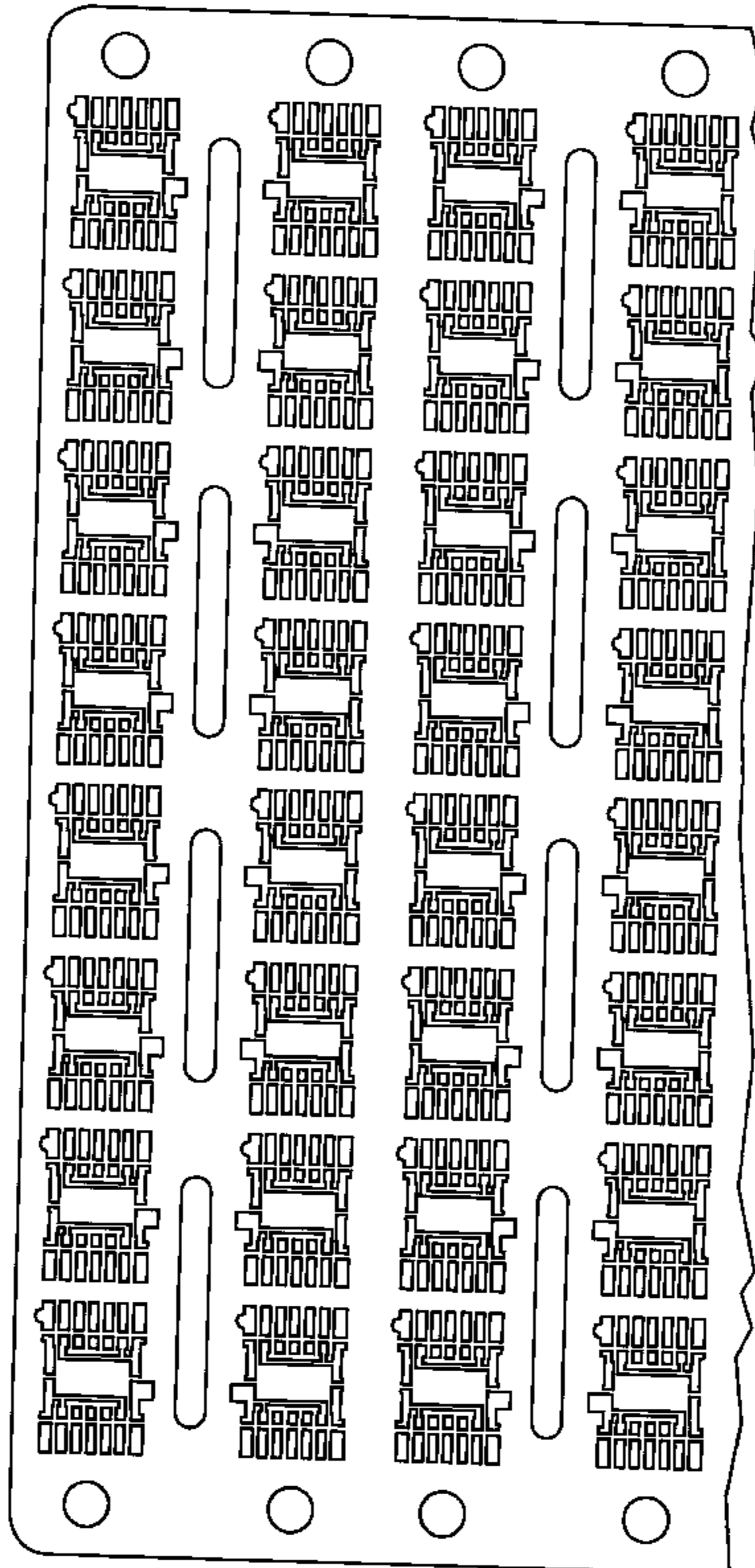
DESCRIPTION

FIG. 1 is a top plan view of a portion of a matrix incorporating a plurality of surface mount package leadframes showing my new design;

FIG. 2 is a top plan view of an enlarged fragment of the portion of a matrix for surface mount package leadframe; and,

FIG. 3 is a perspective view of a matrix incorporating a plurality of surface mount package leadframes showing my new design.

1 Claim, 3 Drawing Sheets



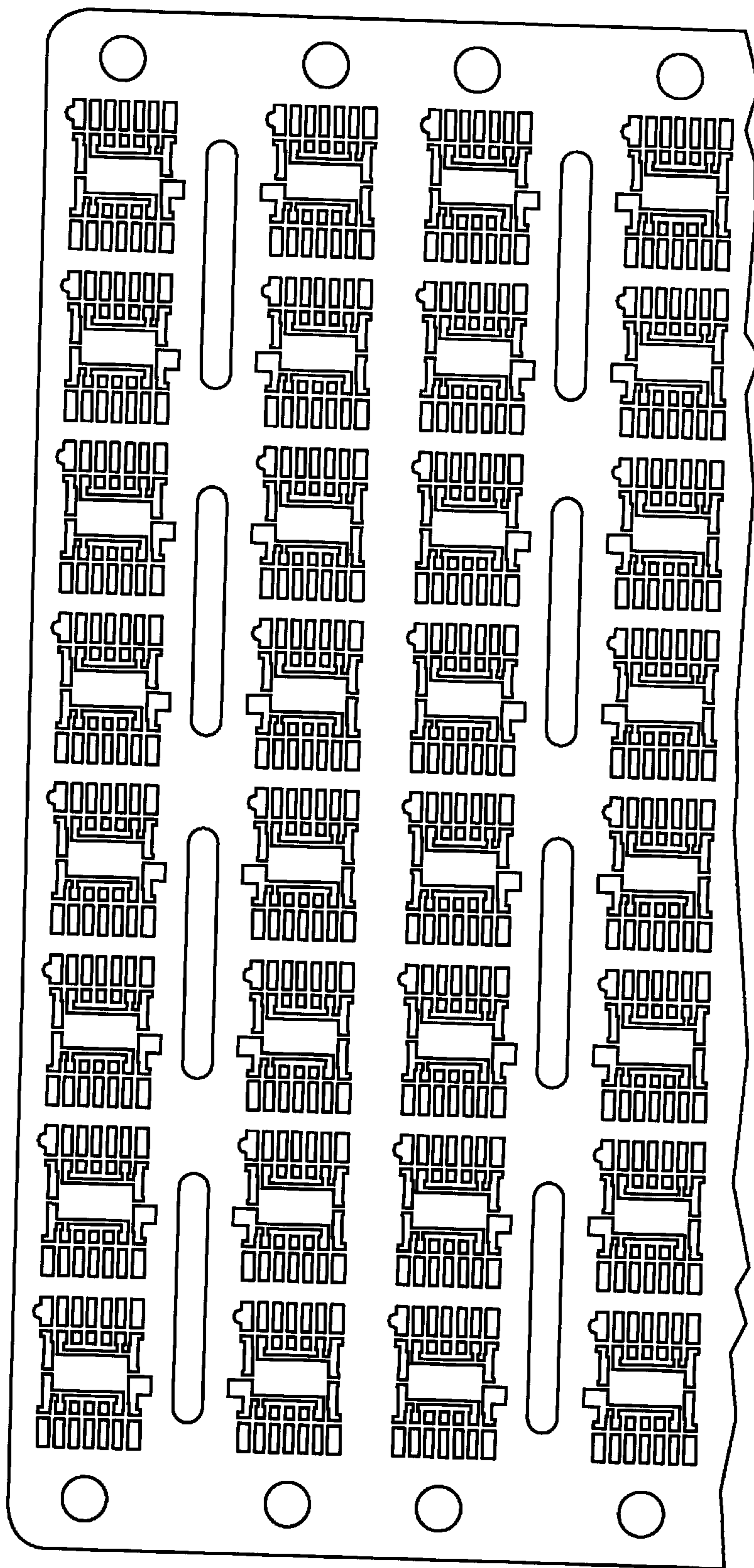


FIG. 1

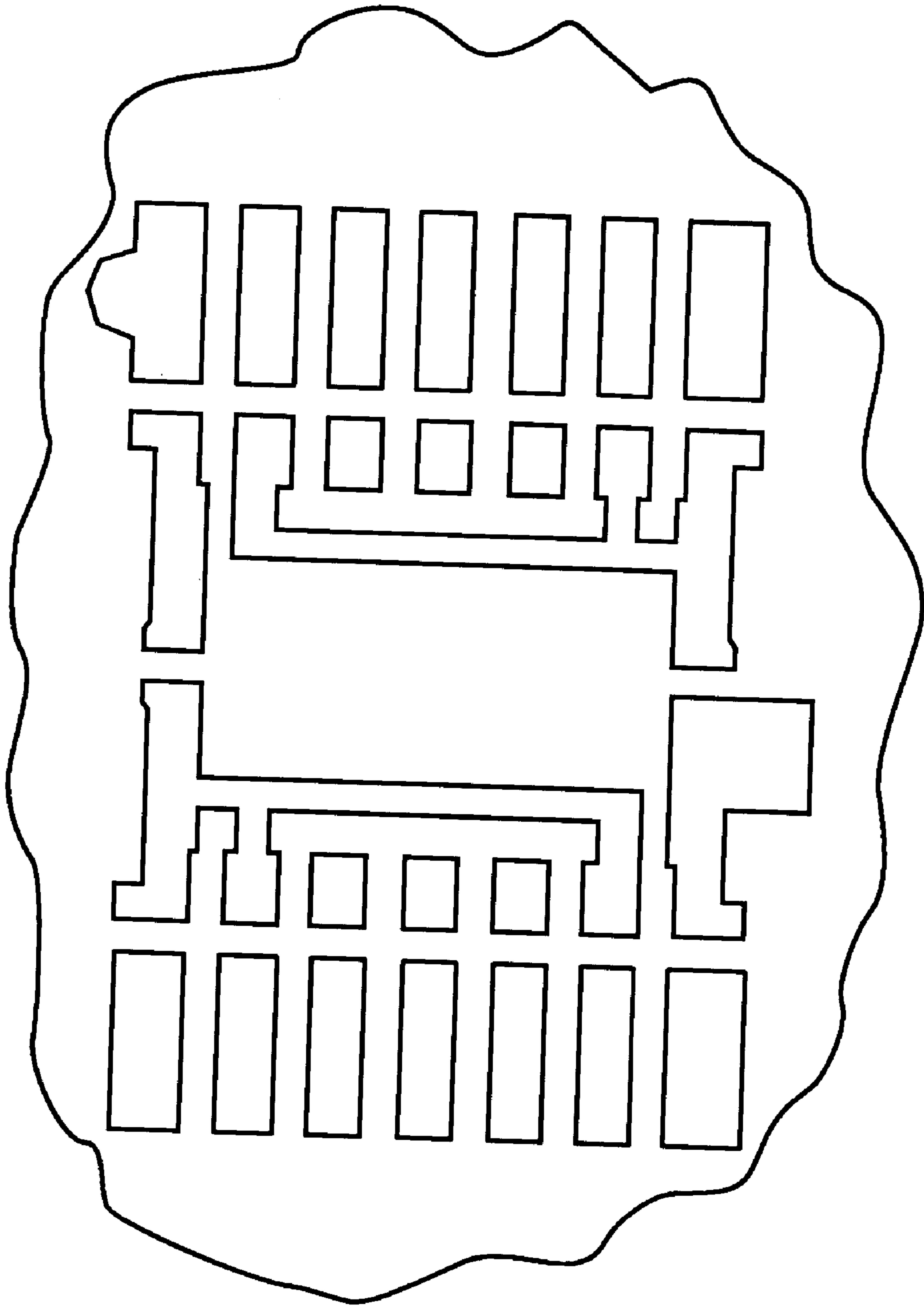


FIG. 2

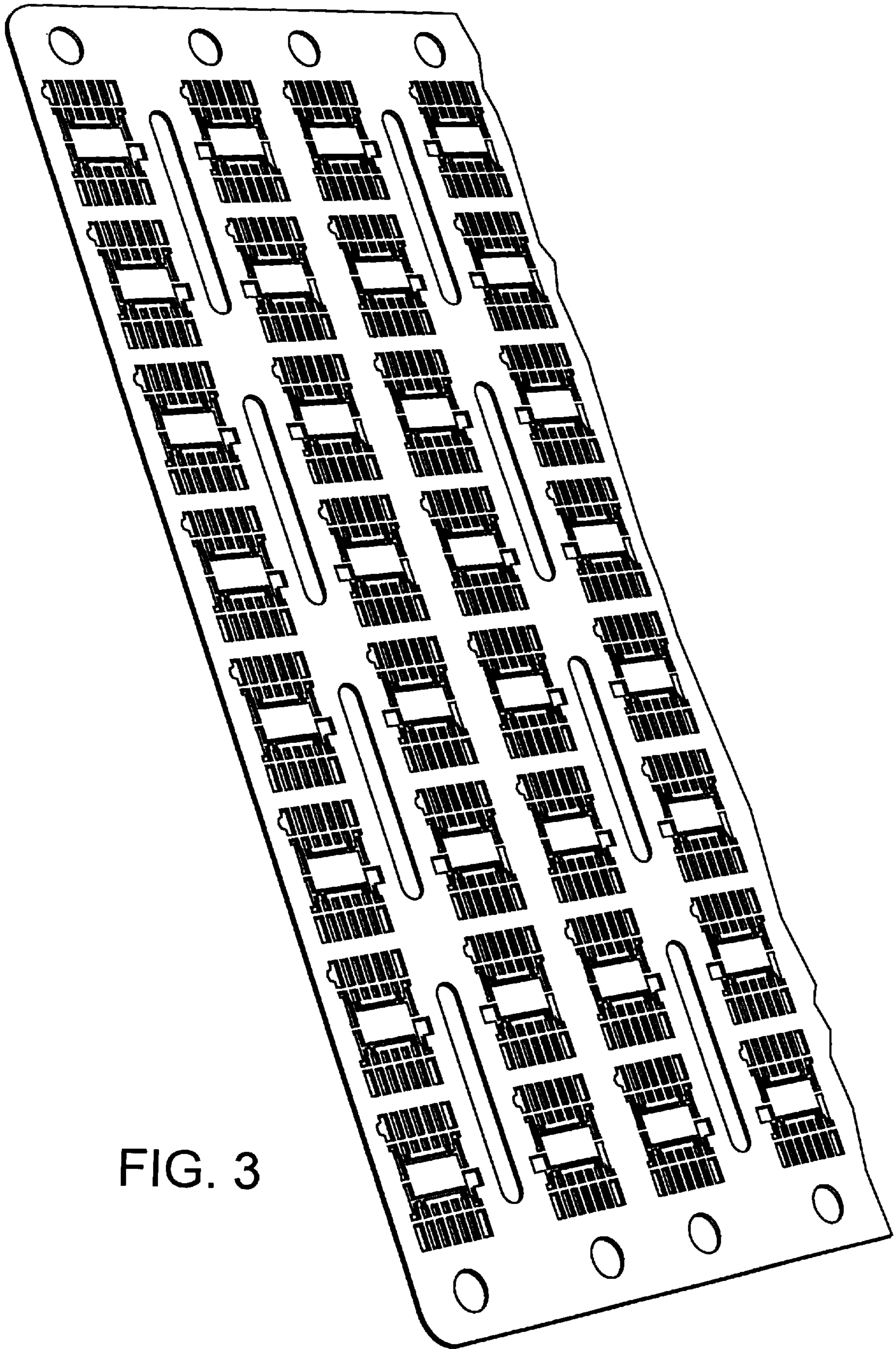


FIG. 3